

BFX-UA300

Hardware Unit Test Report

4 *MIC Test

Hardware version	FW version	Sample No.
V025-DVT2	Google TV	S/N: YUX07V6-2154002568-02S2N

Test DVT2 sample for far field MIC sealing issue: 2021/4/29

SPONGE_MIC_SILICON_140X24X0D5T rubber

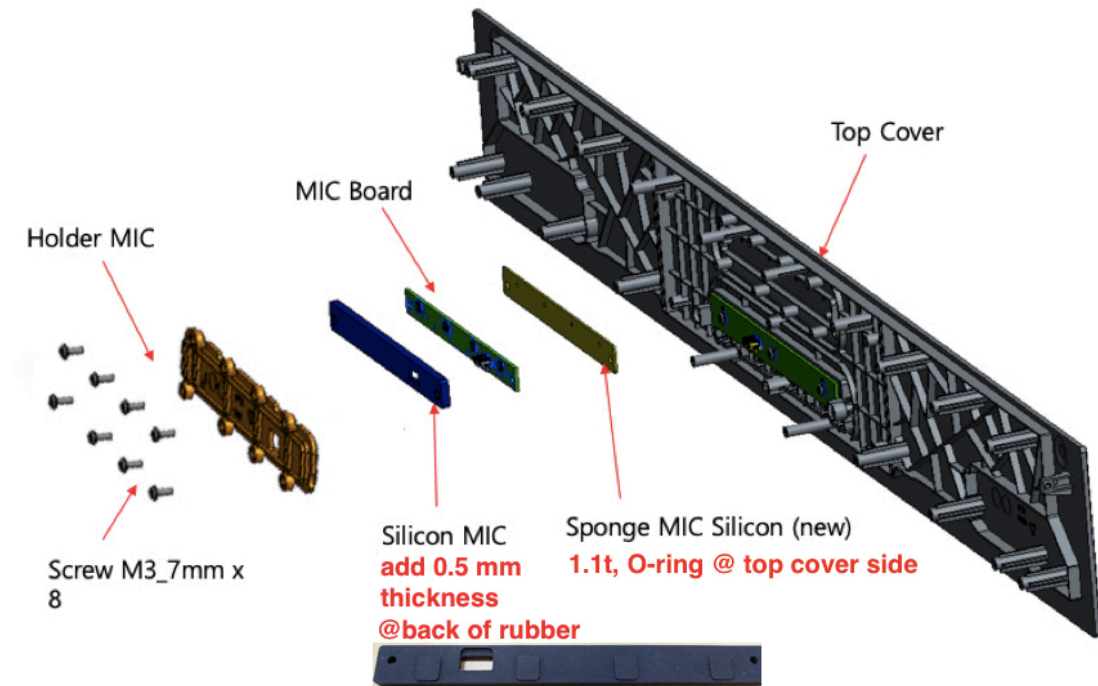
--1.1mm, O-ring@top cover side

SILICON_MIC-UA300 rubber

--Add 0.5mm thickness for each mic components at back of rubber..

Do some MIC sealing solution.

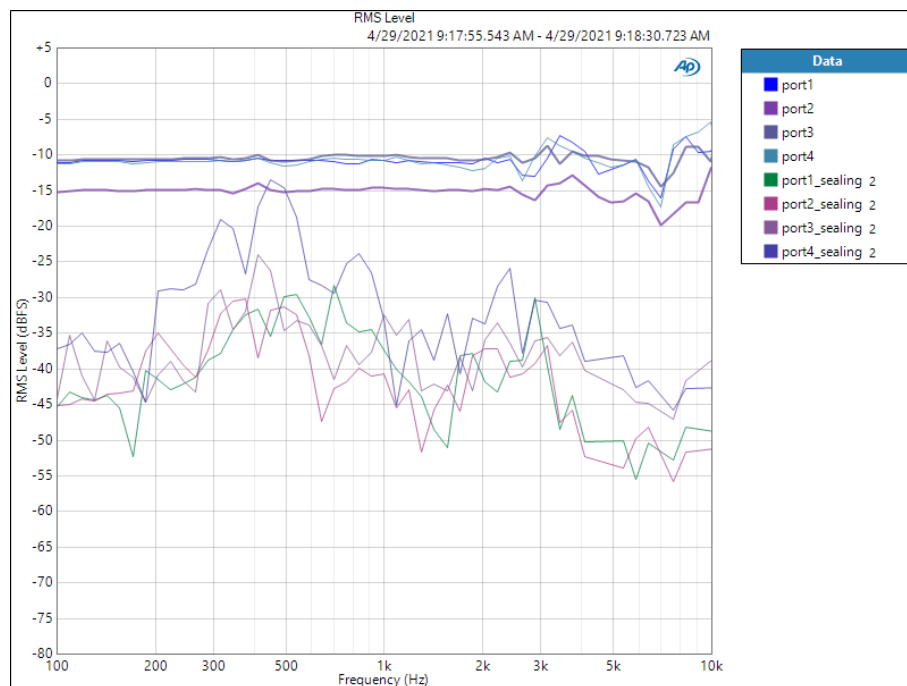
1. Silicon_mic(add 0.5mm X 4 @MIC component)+sponge_mic_1.1t(o-ring@top cover side), see picture b1.
2. Duplicate item 1, see picture b2.
3. Silicon_mic(add 0.5mm X 4 @MIC component)+sponge_mic_1.1t(o-ring@top cover side, add adhesive), see picture b3.



The test follows customer's new rubber, such as single o-ring at top cover side, and add 0.5mm thickness at back of Silicon Mic rubber, for test sealing performance.

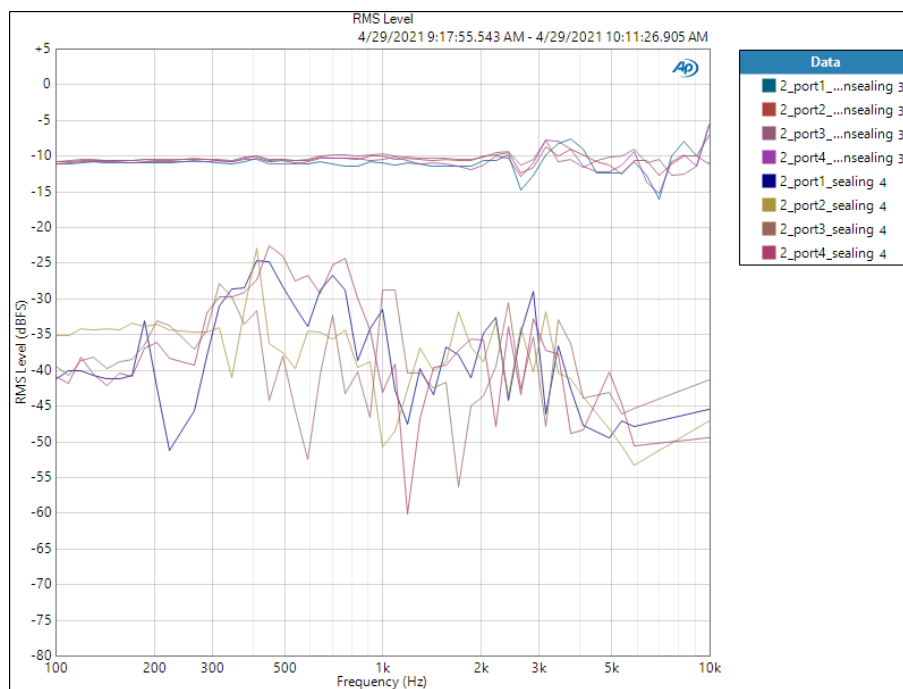
Test results:

1. Silicon_mic(add 0.5mm X 4 @MIC component)+sponge_mic_1.1t(o-ring@top cover side)



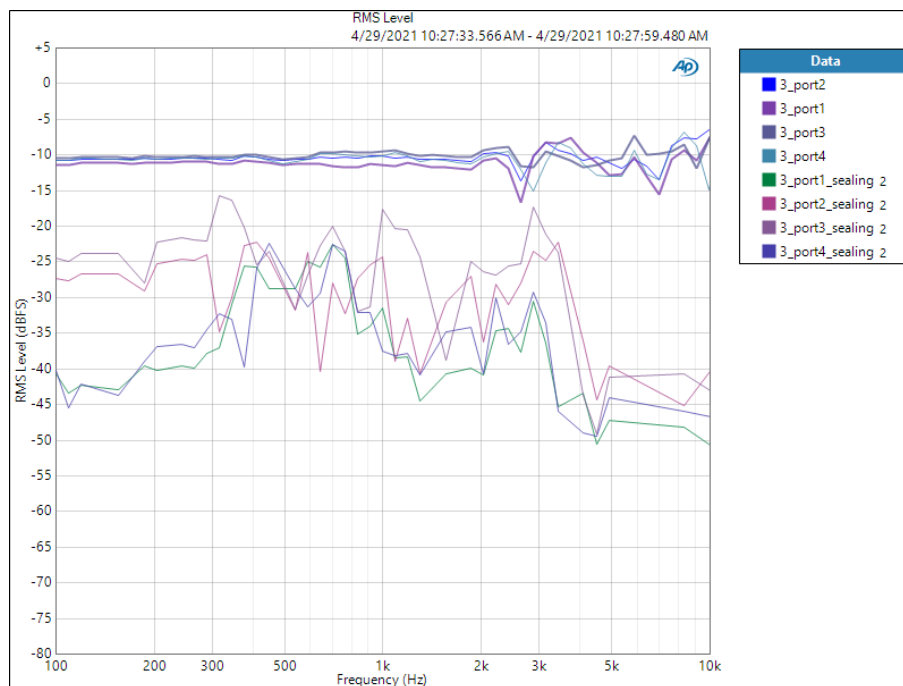
Picture a1. Mic 4 seems bad but all results are not satisfied -35dB.

2. Duplicate item 1



Picture a2. Duplicate as item 1.

3. Silicon_mic(add 0.5mm X 4 @MIC component)+sponge_mic_1.1t(o-ring@top cover side, add adhesive)



Picture a3. Add adhesive at PCB side

Summary

1. By the test results, sponge_mic_silicon_1.1t has no better sealing, even with o-ring@top cover side. The test result cannot achieve to 25dB spec.
Suggest using 0.5t with o-ring@top cover side.
2. Duplicate the same solution, the test has assembly issue.
3. Add adhesive at PCB side, the test result is fail. But mic1 and mic 4 seems better than mic2 and mic3.